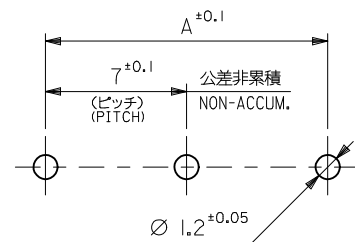


- 注記 NOTES
1. 嵌合相手 : 51067 シリーズ  
MATE WITH : 51067 SERIES
  2. 材質  
MATERIAL  
ウエハー : PBTP (ガラス15%入り)、UL94V-0  
WAFER : PBTP (G.F 15%), UL94V-0  
ピン : 黄銅、ニッケル下地 錫メッキ (t=0.254)  
PIN : BRASS, TIN OVER NICKEL PLATING (t=0.254)
  3. 本製品は 53265-\*\*20の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53265-\*\*20.



基板取付穴推奨寸法 (参考) (t=1.6)  
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)

8.7	54.6	53.2	49.0	53265-0829	8
↑	47.6	46.2	42.0	↑ -0729	7
	40.6	39.2	35.0	↑ -0629	6
	33.6	32.2	28.0	↑ -0529	5
	26.6	25.2	21.0	↑ -0429	4
8.7	19.6	18.2	14.0	↓ -0329	3
6.1	12.6	11.2	7.0	53265-0229	2
(D)	C	B	A	TRAY PACKAGE	CKT. 極数
				ORDER No. オート番号	

REVISED EC NO: J2009-1054 DRWN: MABEI 2009/02/17 CHKD: HYAJIMA 2009/02/18 APPR: NUKITA 2009/02/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	MODEL NO. 53265-**29	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY Y. WADA	DATE '04/04/22	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.) -LEAD FREE-	MOLEX INCORPORATED		
	10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/04/22				
	30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/04/22	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-53265-005	SHEET NO. 1 OF 1	
ANGULAR	± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				